

C1206X202FCGACTU

Aliases (C1206X202FCGAC7800) SMD Comm COG HV Flex, Ceramic, 2,000 pF, 1%, 500 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

General Information		
Series	SMD Comm COG HV Flex	
Style	SMD Chip	
Description	SMD, MLCC, FT-CAP, Ultra- Stable	
Features	FT-CAP, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	42 mg	
Shelf Life	78 Weeks	
MSL	1	

	Specifications	
1206	Capacitance	2,000 pF
3.3mm +/-0.4mm	Measurement Condition	1 kHz 1.0Vrms
1.6mm +/-0.35mm	Tolerance	1%
1.6mm +/-0.25mm	Voltage DC	500 VDC
1.5mm MIN	Dielectric Withstanding Voltage	750 VDC
0.6mm +/-0.25mm	Temperature Range	-55/+125°C
	Temp. Coefficient	COG
T&R, 180mm, Plastic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
2000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour
	Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Dimensions

Packaging Specifications

Packaging Quantity

Chip Size

L

W Т

s

В

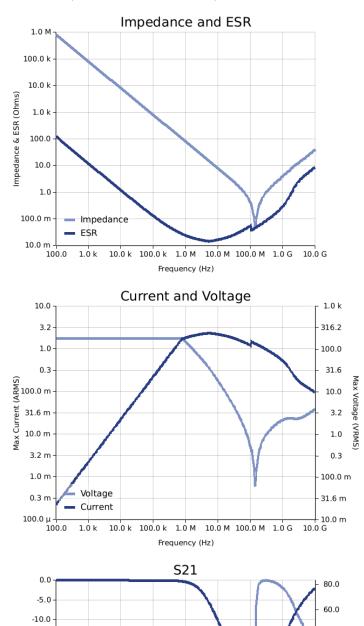
Packaging



C1206X202FCGACTU Aliases (C1206X202FCGAC7800) SMD Comm C0G HV Flex, Ceramic, 2,000 pF, 1%, 500 VDC, C0G, SMD, MLCC, FT-CAP, Ultra-Stable, 1206, 1.5 mm

Simulations

For the complete simulation environment please visit K-SIM.



40.0

20.0

-20.0

-40.0

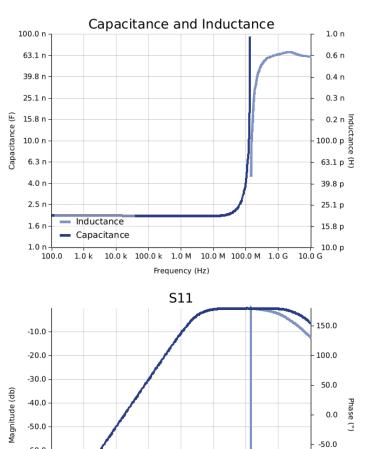
-60.0

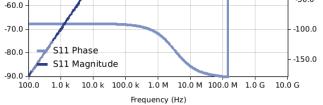
-80.0

10.0 G

o.o

°





Generated 05/25/2025

100.0

S21 Phase

S21 Magnitude

1.0 k 10.0 k 100.0 k 1.0 M 10.0 M 100.0 M 1.0 G

Frequency (Hz)

-15.0 -20.0

-25.0

-30.0

-35.0 -40.0

-45.0

-50.0

Magnitude (db)



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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics.
 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.